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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

## **CONVEYING PARTY DATA**

Name	Execution Date
Chun-Hsien Lin	01/29/2008
Francis Ko	01/29/2008
Kewei Zuo	01/30/2008
Henry Lo	01/30/2008
Jean Wang	01/30/2008

### **RECEIVING PARTY DATA**

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12026361

## **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: 24061.976

NAME OF SUBMITTER: David M. O'Dell

**PATENT** 

**REEL: 020467 FRAME: 0758** 

Total Attachments: 3 source=976Assignment#page1.tif source=976Assignment#page2.tif source=976Assignment#page3.tif

PATENT REEL: 020467 FRAME: 0759

Docket No.: 2007-0369 / 24061.976

Customer No.: 42717

#### ASSIGNMENT

WHEREAS,	we.
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(1)	Chun-Hsien LU	of	No. 20, Sec. 1, Guang Fu Rd. Hsinchu City, Taiwan, R.O.C.
(2)	Francis KO	of	5F-4, No. 92, Jingcheng Rd. West District Taichung City 403, Taiwan, R.O.C.
(3)	Kewei ZUO	of	No. 467 11F-1, Rd Zhongzheng, Yonghe City Taipei County 23455, Taiwan, R.O.C.
(4)	Henry LO	of	7F-6, No. 39, Chien Chung Rd. 1 Hsinchu, Taiwan, R.O.C.
(5)	Jean WANG	of	3F-4 University Rd. Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

## EXTRACTION OF KEY PROCESS PARAMETER

for which we have executed an application for Letters Patent of the United States of America,

	of even date filed herewith; and
X	filed on February 5, 2008 and assigned application number 12/026,361; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America,

R-186393\_1.DOC - 1 -

Docket No.: 2007-0369 / 24061.976

Customer No.: 42717

whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Chun-Hsien LIN

Residence Address:

No. 20, Sec. 1, Guang Fu Rd. Hsinchu City, Taiwan, R.O.C.

Dated: V Chun bein Lin

V Chun Hein him
Inventor Signature

Inventor Name:

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Dated: 1/29/38

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Dated: Jan. 30, 2008

Inventor Signature

Docket No.: 2007-0369 / 24061.976

Customer No.: 42717

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Dated: 1/30/08

Inventor Signature

Inventor Name:

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1/30/08

Hsin-Chu, Taiwan, R.O.C.

Dotad: V

Inventor Signature

R-976 - Assignment 1-17-08 (dmo-kl)

**RECORDED: 02/05/2008** 

- 3 -

PATENT REEL: 020467 FRAME: 0762